17.0 PIC17C42 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias ..... -55 to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on V_{DD} with respect to V_{SS} ..... 0 to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2) ..... -0.6V to +14V
Voltage on RA2 and RA3 with respect to V_{SS} ..... -0.6V to +12V
Voltage on all other pins with respect to V_{SS} ..... -0.6V to V_{DD} + 0.6V
Total power dissipation (Note 1) 1.0W
Maximum current out of V_{SS} pin(s) - Total ..... 250 mA
Maximum current into V_{DD} pin(s) - Total ..... 200 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_0 < 0 or V_0 > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin (except RA2 and RA3) ..... 35 mA
Maximum output current sunk by RA2 or RA3 pins ..... 60 mA
Maximum output current sourced by any I/O pin ..... 20 mA
Maximum current sunk by PORTA and PORTB (combined) ..... 150 mA
Maximum current sourced by PORTA and PORTB (combined) ..... 100 mA
Maximum current sunk by PORTC, PORTD and PORTE (combined) ..... 150 mA
Maximum current sourced by PORTC, PORTD and PORTE (combined) ..... 100 mA

Note 1: *Power dissipation is calculated as follows:* $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

TABLE 17-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	17C42-16	17C42-25
RC	VDD: 4.5V to 5.5V IDD: 6 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 6 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 4 MHz max.
XT	VDD: 4.5V to 5.5V IDD: 24 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 16 MHz max.	VDD: 4.5V to 5.5V IDD: 38 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 25 MHz max.
EC	VDD: 4.5V to 5.5V IDD: 24 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 16 MHz	VDD: 4.5V to 5.5V IDD: 38 mA max. IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 25 MHz max.
LF	VDD: 4.5V to 5.5V IDD: 150 μA max. at 32 kHz (WDT enabled) IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 2 MHz max.	VDD: 4.5V to 5.5V IDD: 150 μA max. at 32 kHz (WDT enabled) IPD: 5 μA max. at 5.5V (WDT disabled) Freq: 2 MHz max

17.1 DC CHARACTERISTICS: PIC17C42-16 (Commercial, Industrial) PIC17C42-25 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD = 4.5V to 5.5V				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	4.5	–	5.5	V	
D002	VDR	RAM Data Retention Voltage (Note 1)	1.5 *	–	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to guarantee Power-On Reset	–	VSS	–	V	See section on Power-On Reset for details
D004	SVDD	VDD rise rate to guarantee Power-On Reset	0.060*	–	–	mV/ms	See section on Power-On Reset for details
D010	IDD	Supply Current	–	3	6	mA	FOSC = 4 MHz (Note 4)
D011		(Note 2)	–	6	12 *	mA	FOSC = 8 MHz
D012			–	11	24 *	mA	FOSC = 16 MHz
D013			–	19	38	mA	FOSC = 25 MHz
D014			–	95	150	µA	FOSC = 32 kHz WDT enabled (EC osc configuration)
D020	IPD	Power Down Current	–	10	40	µA	VDD = 5.5V, WDT enabled
D021		(Note 3)	–	< 1	5	µA	VDD = 5.5V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1=external square wave, from rail to rail; all I/O pins tristated, pulled to VDD or VSS, T0CKI = VDD, $\overline{MCLR}$ = VDD; WDT enabled/disabled as specified.
Current consumed from the oscillator and I/O's driving external capacitive or resistive loads need to be considered.
For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD / (2 • R).
For capacitive loads, The current can be estimated (for an individual I/O pin) as (CL • VDD) • f
CL = Total capacitive load on the I/O pin; f = average frequency on the I/O pin switches.
The capacitive currents are most significant when the device is configured for external execution (includes extended microcontroller mode).

3: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, all I/O pins in hi-impedance state and tied to VDD or VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula IR = VDD/2Rext (mA) with Rext in kOhm.

17.2 DC CHARACTERISTICS: PIC17C42-16 (Commercial, Industrial)
PIC17C42-25 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial Operating voltage VDD range as described in Section 17.1				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
	VIL	**Input Low Voltage** I/O ports					
D030		with TTL buffer	VSS	–	0.8	V	
D031		with Schmitt Trigger buffer	VSS	–	0.2 VDD	V	
D032		MCLR, OSC1 (in EC and RC mode)	VSS	–	0.2 VDD	V	Note1
D033		OSC1 (in XT, and LF mode)	–	0.5 VDD	–	V	
	VIH	**Input High Voltage** I/O ports		–			
D040		with TTL buffer	2.0	–	VDD	V	
D041		with Schmitt Trigger buffer	0.8 VDD	–	VDD	V	
D042		MCLR	0.8 VDD	–	VDD	V	Note1
D043		OSC1 (XT, and LF mode)	–	0.5 VDD	–	V	
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15 VDD*	–	–	V	
		Input Leakage Current (Notes 2, 3)					
D060	IIL	I/O ports (except RA2, RA3)	–	–	±1	µA	VSS ≤ VPIN ≤ VDD, I/O Pin at hi-impedance PORTB weak pull-ups disabled
D061		MCLR	–	–	±2	µA	VPIN = VSS or VPIN = VDD
D062		RA2, RA3			±2	µA	VSS ≤ VRA2, VRA3 ≤ 12V
D063		OSC1, TEST	–	–	±1	µA	VSS ≤ VPIN ≤ VDD
D064		MCLR	–	–	10	µA	VMCLR = VPP = 12V (when not programming)
D070	IPURB	PORTB weak pull-up current	60	200	400	µA	VPIN = VSS, RBPU = 0

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

†† Design guidance to attain the AC timing specifications. These loads are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt trigger input. It is not recommended that the PIC17CXX devices be driven with external clock in RC mode.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: These specifications are for the programming of the on-chip program memory EPROM through the use of the table write instructions. The complete programming specifications can be found in: PIC17CXX Programming Specifications (Literature number DS30139).

5: The MCLR/Vpp pin may be kept in this range at times other than programming, but this is not recommended.

6: For TTL buffers, the better of the two specifications may be used.

DC CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated)
Operating temperature
-40°C ≤ TA ≤ +85°C for industrial and
0°C ≤ TA ≤ +70°C for commercial
Operating voltage VDD range as described in Section 17.1

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
		Output Low Voltage					
D080	VOL	I/O ports (except RA2 and RA3)	–	–	0.1 VDD	V	IOL = 4 mA
D081		with TTL buffer	–	–	0.4	V	IOL = 6 mA, VDD = 4.5V Note 6
D082		RA2 and RA3	–	–	3.0	V	IOL = 60.0 mA, VDD = 5.5V
D083		OSC2/CLKOUT (RC and EC osc modes)	–	–	0.4	V	IOL = 2 mA, VDD = 4.5V
		Output High Voltage (Note 3)					
D090	VOH	I/O ports (except RA2 and RA3)	0.9 VDD	–	–	V	IOH = -2 mA
D091		with TTL buffer	2.4	–	–	V	IOH = -6.0 mA, VDD = 4.5V Note 6
D092		RA2 and RA3	–	–	12	V	Pulled-up to externally applied voltage
D093		OSC2/CLKOUT (RC and EC osc modes)	2.4	–	–	V	IOH = -5 mA, VDD = 4.5V
		Capacitive Loading Specs on Output Pins					
D100	COSC2	OSC2 pin	–	–	25 ††	pF	In EC or RC osc modes when OSC2 pin is outputting CLKOUT. external clock is used to drive OSC1.
D101	CIO	All I/O pins and OSC2 (in RC mode)	–	–	50 ††	pF	
D102	CAD	System Interface Bus (PORTC, PORTD and PORTE)	–	–	100 ††	pF	In Microprocessor or Extended Microcontroller mode
		Internal Program Memory Programming Specs (Note 4)					
D110	VPP	Voltage on $\overline{MCLR}$/VPP pin	12.5	–	13.5	V	Note 5
D111	VDDP	Supply voltage during programming	4.75	5.0	5.25	V	
D112	IPP	Current into $\overline{MCLR}$/VPP pin	–	25 ‡	50 ‡	mA	
D113	IDDP	Supply current during programming	–	–	30 ‡	mA	
D114	TPROG	Programming pulse width	10	100	1000	µs	Terminated via internal/external interrupt or a reset

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

†† Design guidance to attain the AC timing specifications. These loads are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt trigger input. It is not recommended that the PIC17CXX devices be driven with external clock in RC mode.

2: The leakage current on the $\overline{MCLR}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: These specifications are for the programming of the on-chip program memory EPROM through the use of the table write instructions. The complete programming specifications can be found in: PIC17CXX Programming Specifications (Literature number DS30139).

5: The $\overline{MCLR}$/Vpp pin may be kept in this range at times other than programming, but this is not recommended.

6: For TTL buffers, the better of the two specifications may be used.

17.3 Timing Parameter Symbology

The timing parameter symbols have been created using one of the following formats:

1. TppS2ppS
2. TppS

T			
F	Frequency	T	Time

Lowercase symbols (pp) and their meanings:

pp			
ad	Address/Data	ost	Oscillator Start-Up Timer
al	ALE	pwrt	Power-Up Timer
cc	Capture1 and Capture2	rb	PORTB
ck	CLKOUT or clock	rd	$\overline{RD}$
dt	Data in	rw	$\overline{RD}$ or $\overline{WR}$
in	INT pin	t0	T0CKI
io	I/O port	t123	TCLK12 and TCLK3
mc	$\overline{MCLR}$	wdt	Watchdog Timer
oe	$\overline{OE}$	wr	$\overline{WR}$
os	OSC1		

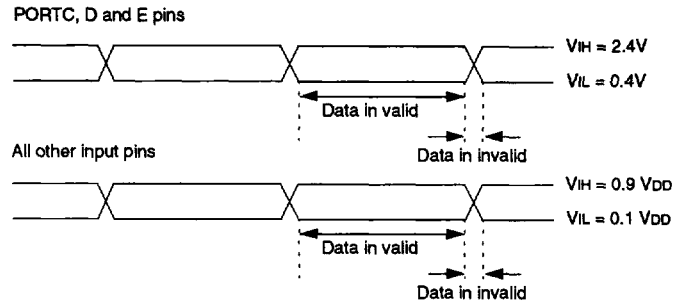
Uppercase symbols and their meanings:

S			
D	Driven	L	Low
E	Edge	P	Period
F	Fall	R	Rise
H	High	V	Valid
I	Invalid (Hi-impedance)	Z	High Impedance

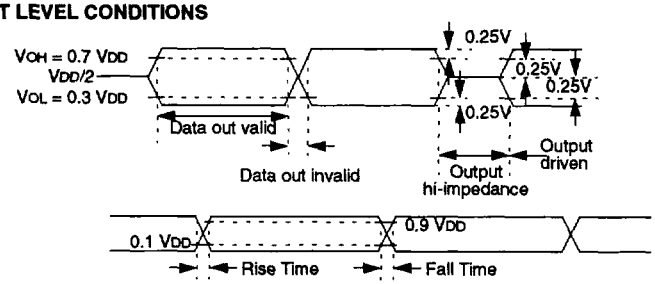
FIGURE 17-1: PARAMETER MEASUREMENT INFORMATION

All timings are measure between high and low measurement points as indicated in the figures below.

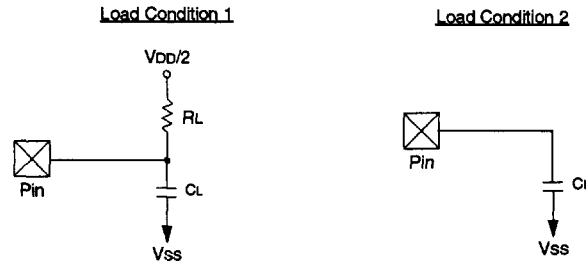
INPUT LEVEL CONDITIONS



OUTPUT LEVEL CONDITIONS



LOAD CONDITIONS

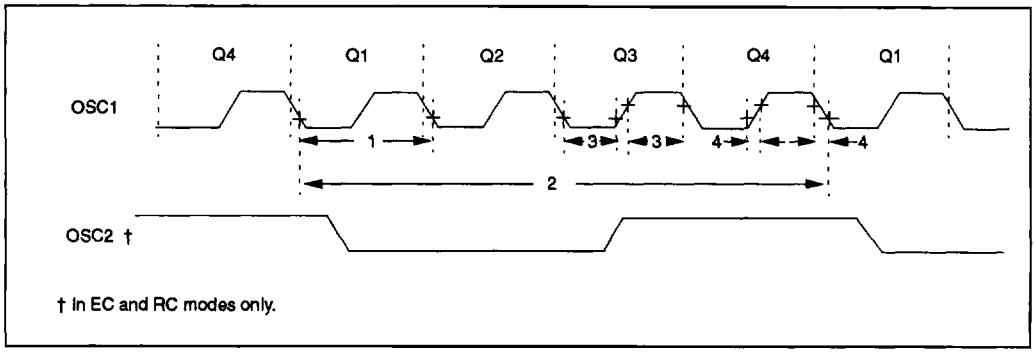


$R_L = 464$

$50 \leq C_L \leq 100$ pF

17.4 Timing Diagrams and Specifications

FIGURE 17-2: EXTERNAL CLOCK TIMING



† In EC and RC modes only.

TABLE 17-2: EXTERNAL CLOCK TIMING REQUIREMENTS

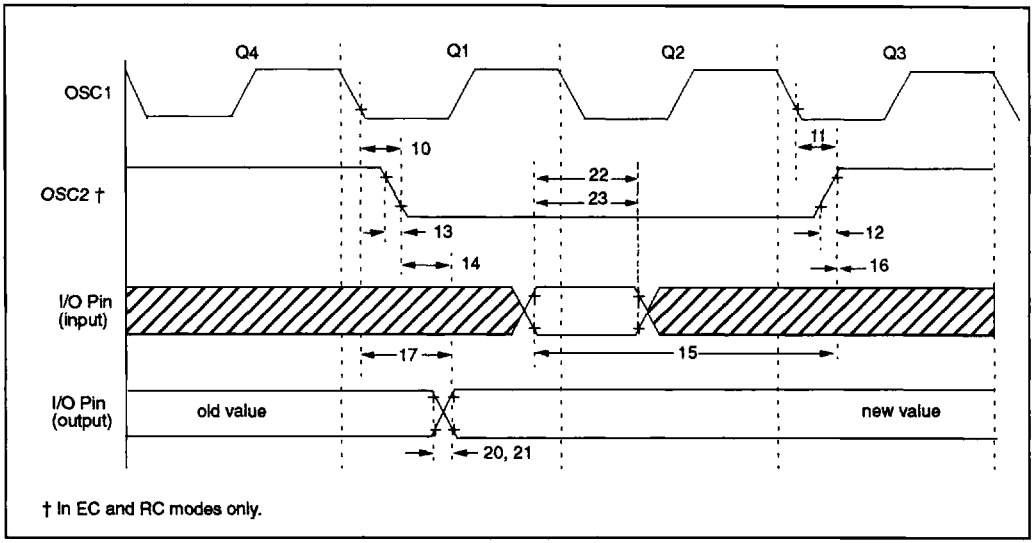
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	**External CLKIN Frequency**	DC	—	16	MHz	EC osc mode - PIC17C42-16
		(Note 1)	DC	—	25	MHz	- PIC17C42-25
		Oscillator Frequency	DC	—	4	MHz	RC osc mode
		(Note 1)	1	—	16	MHz	XT osc mode - PIC17C42-16
			1	—	25	MHz	- PIC17C42-25
			DC	—	2	MHz	LF osc mode
1	Tosc	**External CLKIN Period**	62.5	—	—	ns	EC osc mode - PIC17C42-16
		(Note 1)	40	—	—	ns	- PIC17C42-25
		Oscillator Period	250	—	—	ns	RC osc mode
		(Note 1)	62.5	—	1,000	ns	XT osc mode - PIC17C42-16
			40	—	1,000	ns	- PIC17C42-25
			500	—	—	ns	LF osc mode
2	Tcy	**Instruction Cycle Time (Note 1)**	160	4/Fosc	DC	ns	
3	TosL, TosH	Clock in (OSC1) High or Low Time	10 ‡	—	—	ns	EC oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	—	5 ‡	ns	EC oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: Instruction cycle period (Tcy) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1 pin.
When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 17-3: CLKOUT AND I/O TIMING



† In EC and RC modes only.

TABLE 17-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10	TosH2ckL	OSC1↑ to CLKOUT↓	—	15 ‡	30 ‡	ns	Note 1
11	TosH2ckH	OSC1↑ to CLKOUT↑	—	15 ‡	30 ‡	ns	Note 1
12	TckR	CLKOUT rise time	—	5 ‡	15 ‡	ns	Note 1
13	TckF	CLKOUT fall time	—	5 ‡	15 ‡	ns	Note 1
14	TckH2ioV	CLKOUT↑ to Port out valid	—	—	0.5 TCY+20‡	ns	Note 1
15	TioV2ckH	Port in valid before CLKOUT↑	0.25 TCY+25 ‡	—	—	ns	Note 1
16	TckH2iol	Port in hold after CLKOUT↑	0 ‡	—	—	ns	Note 1
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	—	—	100 ‡	ns	
20	TioR	Port output rise time	—	10 ‡	35 ‡	ns	
21	TioF	Port output fall time	—	10 ‡	35 ‡	ns	
22	TinHL	INT pin high or low time	25 *	—	—	ns	
23	TrbHL	RB<7:0> change INT high or low time	25 *	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

Note 1: Measurements are taken in EC Mode where OSC2 output is 4 x Tosc.

FIGURE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER TIMING

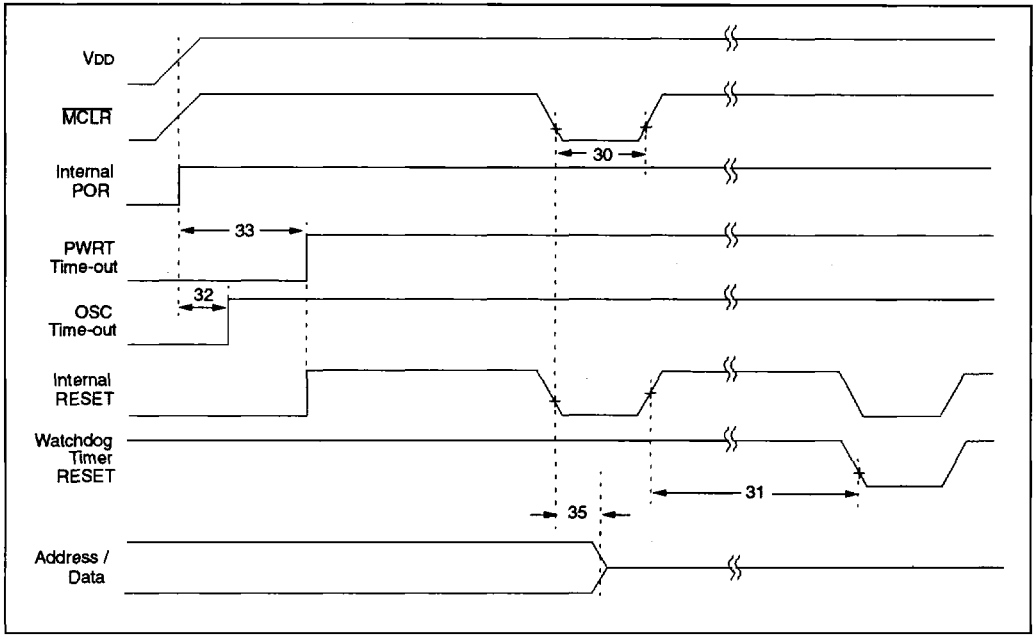


TABLE 17-4: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER AND POWER-UP TIMER REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
30	TmcL	$\overline{MCLR}$ Pulse Width (low)	100 *	—	—	ns	
31	Twdt	Watchdog Timer Timeout Period (Prescale = 1)	5 *	12	25 *	ms	
32	Tost	Oscillation Start-Up Timer Period		1024 Tosc §		ms	Tosc = OSC1 period
33	Tpwrt	Power-Up Timer Period	40 *	96	200 *	ms	
35	TmcL2adl	$\overline{MCLR}$ to System Interface bus (AD<15:0>) invalid	—	—	100 *	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

§ This specification guaranteed by design.

FIGURE 17-5: TIMER0 CLOCK TIMINGS

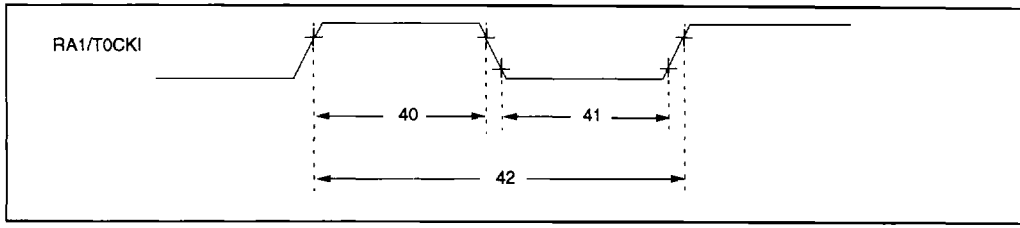


TABLE 17-5: TIMER0 CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 Tcy + 20 §	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 Tcy + 20 §	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		Tcy + 40 § / N	—	—	ns	N = prescale value (1, 2, 4, ..., 256)

* These parameters are characterized but not tested.

† *Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.*

§ This specification guaranteed by design.

FIGURE 17-6: TIMER1, TIMER2, AND TIMER3 CLOCK TIMINGS

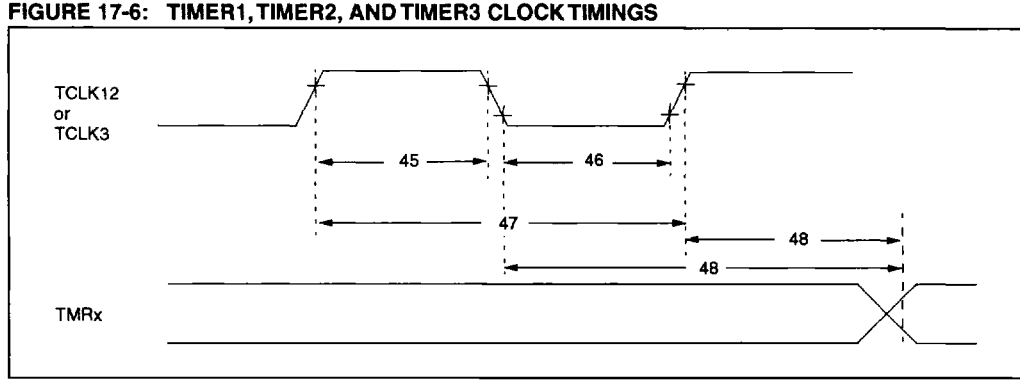


TABLE 17-6: TIMER1, TIMER2, AND TIMER3 CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ †	Max	Units	Conditions
45	Tt1l23H	TCLK12 and TCLK3 high time	0.5 Tcy + 20 §	—	—	ns	
46	Tt1l23L	TCLK12 and TCLK3 low time	0.5 Tcy + 20 §	—	—	ns	
47	Tt1l23P	TCLK12 and TCLK3 input period	Tcy + 40 § / N	—	—	ns	N = prescale value (1, 2, 4, 8)
48	TckE2tmrI	Delay from selected External Clock Edge to Timer increment	2 Tosc §		6 Tosc §		

* These parameters are characterized but not tested.

† *Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.*

§ This specification guaranteed by design.

FIGURE 17-7: CAPTURE TIMINGS

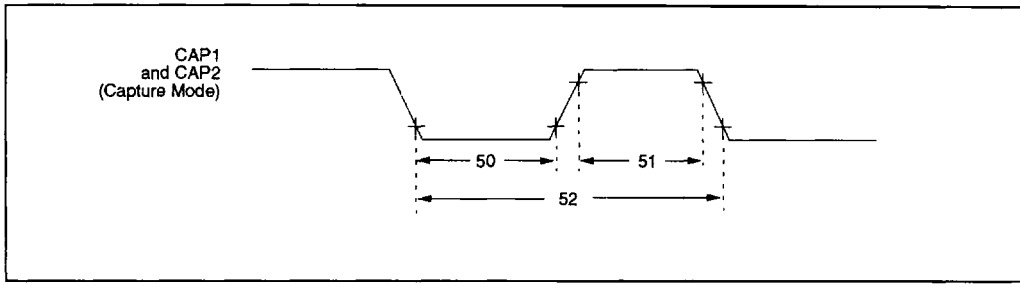


TABLE 17-7: CAPTURE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
50	TccL	Capture1 and Capture2 input low time	10 *	—	—	ns	
51	TccH	Capture1 and Capture2 input high time	10 *	—	—	ns	
52	TccP	Capture1 and Capture2 input period	2 Tcy § N	—	—	ns	N = prescale value (4 or 16)

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification guaranteed by design.

FIGURE 17-8: PWM TIMINGS

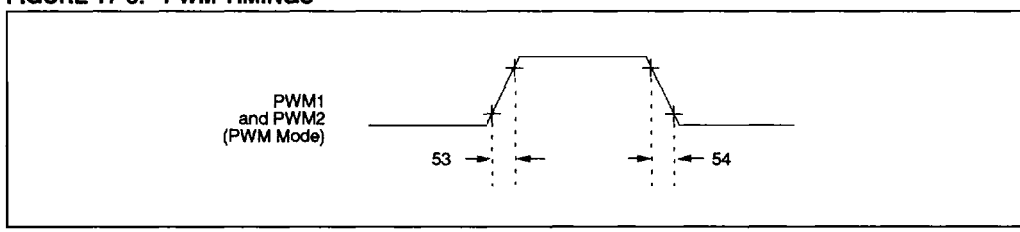


TABLE 17-8: PWM REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
53	TccR	PWM1 and PWM2 output rise time	—	10 *	35 *§	ns	
54	TccF	PWM1 and PWM2 output fall time	—	10 *	35 *§	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification guaranteed by design.

FIGURE 17-9: SCI MODULE: SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING

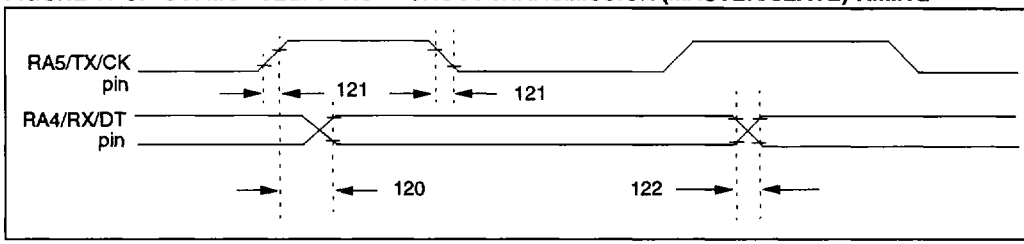


TABLE 17-9: SERIAL PORT SYNCHRONOUS TRANSMISSION REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
120	TckH2dtV	SYNC XMIT (MASTER & SLAVE) Clock high to data out valid	—	—	65	ns	
121	TckRF	Clock out rise time and fall time (Master Mode)	—	10	35	ns	
122	TdtRF	Data out rise time and fall time	—	10	35	ns	

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FIGURE 17-10: SCI MODULE: SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING

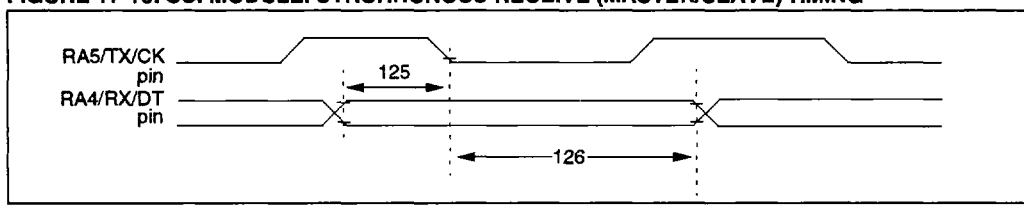

TABLE 17-10: SERIAL PORT SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
125	TdtV2ckL	SYNC RCV (MASTER & SLAVE) Data hold before CK↓ (DT hold time)	15	—	—	ns	
126	TckL2dtl	Data hold after CK↓ (DT hold time)	15	—	—	ns	

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 17-11: MEMORY INTERFACE WRITE TIMING

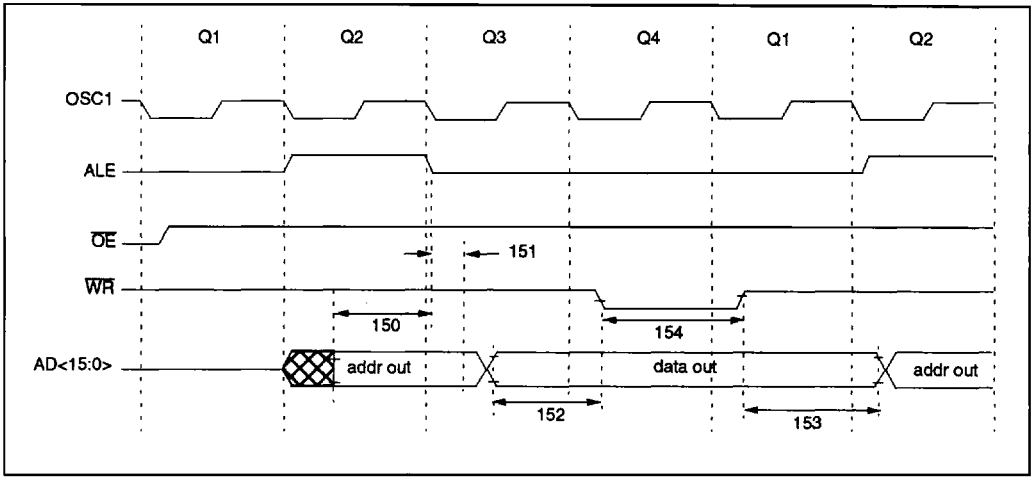

TABLE 17-11: MEMORY INTERFACE WRITE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
150	TadV2alL	AD<15:0> (address) valid to ALE↓ (address setup time)	0.25 Tcy-30	—	—	ns	
151	TalL2adI	ALE↓ to address out invalid (address hold time)	0	—	—	ns	
152	TadV2wrL	Data out valid to $\overline{WR}$↓ (data setup time)	0.25 Tcy-40	—	—	ns	
153	TwrH2adI	$\overline{WR}$↑ to data out invalid (data hold time)	—	0.25 Tcy §	—	ns	
154	TwrL	$\overline{WR}$ pulse width	—	0.25 Tcy §	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification is guaranteed by design.

FIGURE 17-12: MEMORY INTERFACE READ TIMING

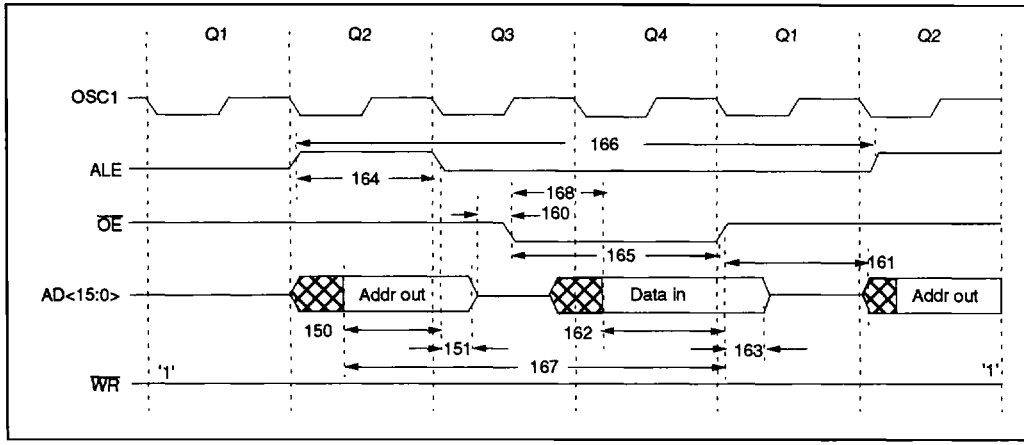

TABLE 17-12: MEMORY INTERFACE READ REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
150	TadV2alL	AD<15:0> (address) valid to ALE↓ (address setup time)	0.25 Tcy-30	—	—	ns	
151	TalL2adI	ALE↓ to address out invalid (address hold time)	0	—	—	ns	
160	TadZ2oeL	AD<15:0> high impedance to $\overline{OE}$↓	10	—	—	ns	
161	ToeH2adD	$\overline{OE}$↑ to AD<15:0> driven	0.25 Tcy-15	—	—	ns	
162	TadV2oeH	Data in valid before $\overline{OE}$↑ (data setup time)	35	—	—	ns	
163	ToeH2adI	$\overline{OE}$↑to data in invalid (data hold time)	0	—	—	ns	
164	TalH	ALE pulse width	—	0.25 Tcy §	—	ns	
165	ToeL	$\overline{OE}$ pulse width	0.5 Tcy-35 §	—	—	ns	
166	TalH2alH	ALE↑ to ALE↑ (cycle time)	—	Tcy §	—	ns	
167	Tacc	Address access time	—	—	0.75 Tcy-40	ns	
168	Toe	Output enable access time ($\overline{OE}$ low to Data Valid)	—	—	0.5 Tcy - 60	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification guaranteed by design.